

4

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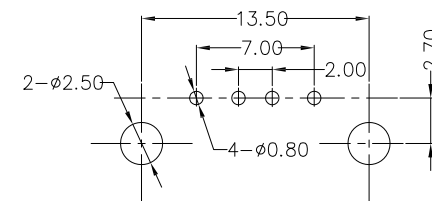
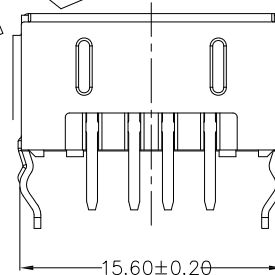
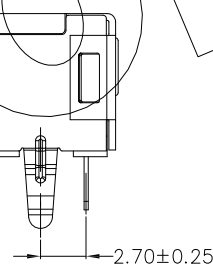
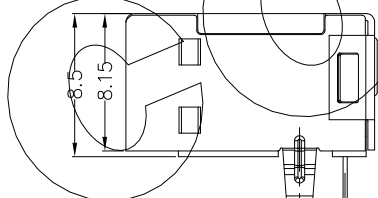
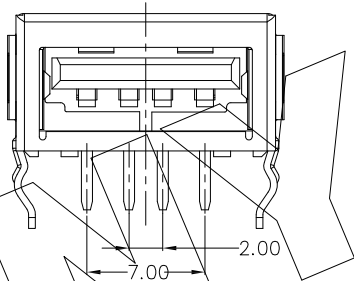
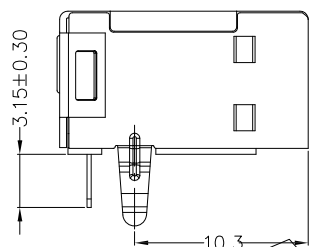
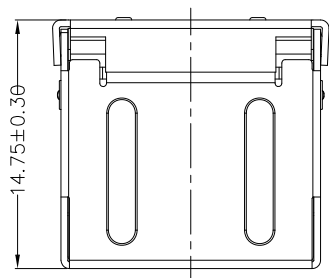
REVISION DATA

REV	DESCRIPTION	DATE
A0	NEW DRAWING	2016-4-15

- 1: 外壳材质代码: A:黄铜C2680, B:磷铜C5191,
D:单光铁, E:双光铁
- 2: 外壳电镀代码: A:镀镍12H, B:镀镍24H, C:镀镍48H,
D:镀雾镍, E:镀锡, F:镀雾锡
- 3: 后壳材质及电镀代码: A:SPCC镀锡, B:SPCC镀雾锡, C:SPCC镀锡,
D:SPCC镀雾锡, E:黄铜镀锡, F:黄铜镀雾锡,
G:黄铜镀锡, H:黄铜镀雾锡
- 4: 中夹片材质及电镀代码: A:SPCC镀锡, B:SPCC镀雾锡, C:SPCC镀锡,
D:SPCC镀雾锡, E:黄铜镀锡, F:黄铜镀雾锡,
G:黄铜镀锡, H:黄铜镀雾锡, I:磷铜镀锡,
J:磷铜镀锡, K:不锈钢, L:不锈钢镀锡
- 5: 胶芯材质代码: A:PBT, B:LCP
- 6: 胶芯颜色代码: 1:白色, 2:黑色, 3:本色
- 7: 端子材质代码: 1:黄铜C2680, 2:磷铜C5191
- 8: 端子电镀代码: A:半金锡G/F, B:半金锡3u",
C:半金锡15u", D:半金锡30u"
- 9: 环保代码: N:非环保, R:ROHS, S:SONY, F:ROHS+无卤

NOTES:

1. MATERIAL SPECIFICATION:
1) HOUSING: THERMOPLASTIC (UL94V-0)
2) SHELL: SEE PART NO.
PLATING: NICKEL
3) TERMINAL: COPPER ALLOY
PLATING: GOLD/TIN PLATED;
2. ELECTRICAL CHARACTERISTIC:
1) VOLTAGE CURRENT RATING: 1AMP, 30V DC;
2) INSULATION RESISTANCE: 1000M Ω MIN;
3) CONTACT RESISTANCE: 30m Ω MAX;
4) WITHSTANDING VOLTAGE: 500V AC;
3. MECHANICAL:
1) MATING FORCE: 3.5 KG MAX
2) UNMATING FORCE: 1.02 KG MIN.



PCB LAYOUT

ANYCONN® 东莞市恩康电子有限公司

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DONGGUAN ANYCONN ELECTRONICS CO.,LTD

TOLERANCE	PROJECTON		TITLE:
ANGLE ±5°	DATE :	2016-4-15	USB A/F DIP 90°单层全包
X.XXX ±0.10	DRAWN :	ZHANG	PART NO: USB079
X.XX ±0.20	CHECKED :		DRAWING NO:
X.X ±0.30	APPROVED :		REV: A0
X. ±0.50			UNIT: mm
			SCALE: 3:1
			SIZE: A4